

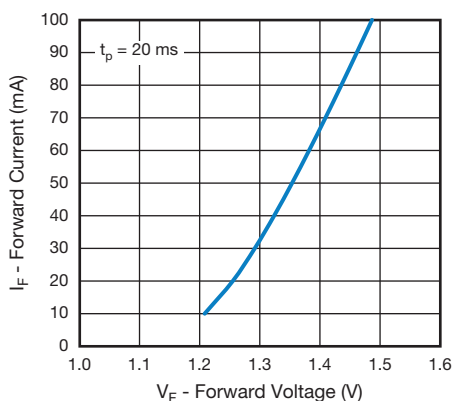
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 4 - Forward Current vs. Forward Voltage

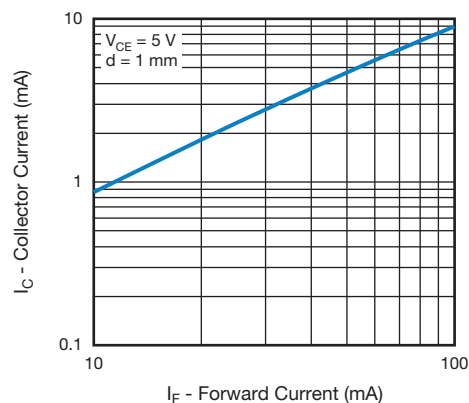


Fig. 7 - Collector Current vs. Forward Current

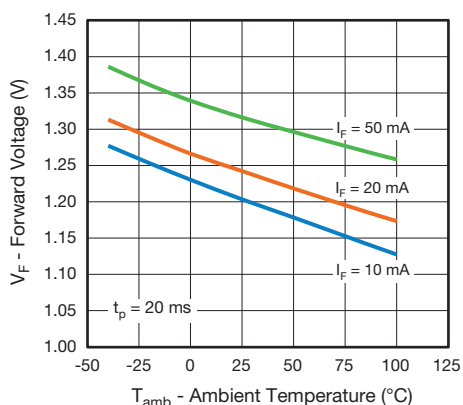


Fig. 5 - Forward Voltage vs. Ambient Temperature

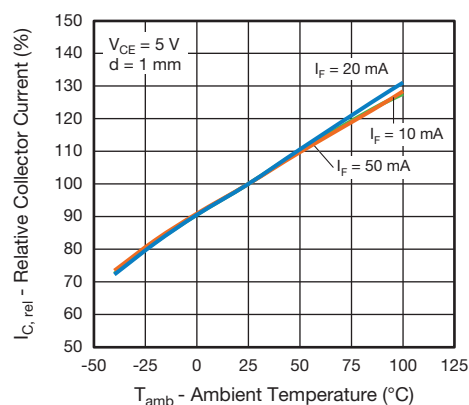


Fig. 8 - Relative Collector Current vs. Ambient Temperature

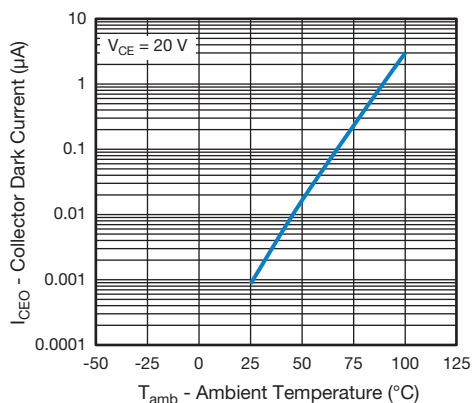


Fig. 6 - Collector Dark Current vs. Ambient Temperature

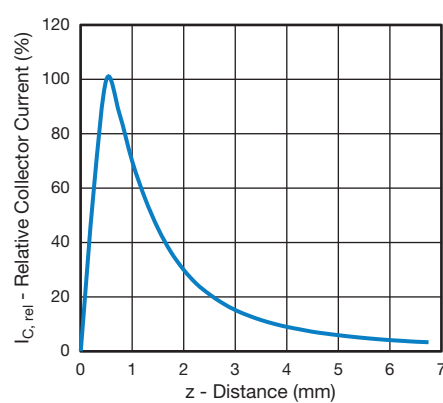


Fig. 9 - Relative Collector Current vs. Distance

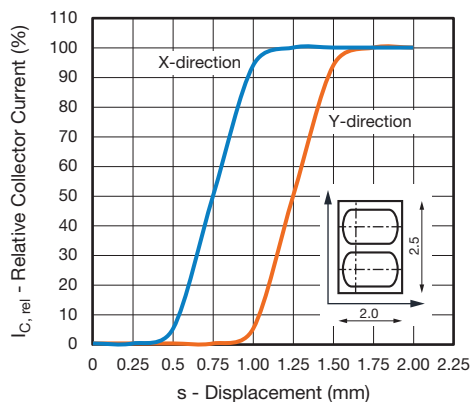


Fig. 10 - Relative Collector Current vs. Displacement

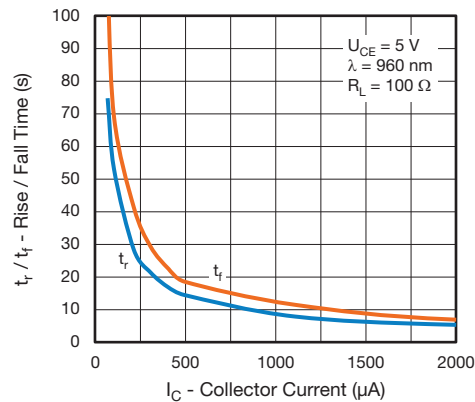


Fig. 11 - Rise / Fall Time vs. Collector Current

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 4

Floor life: 72 h

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, RH < 60 %

DRYING

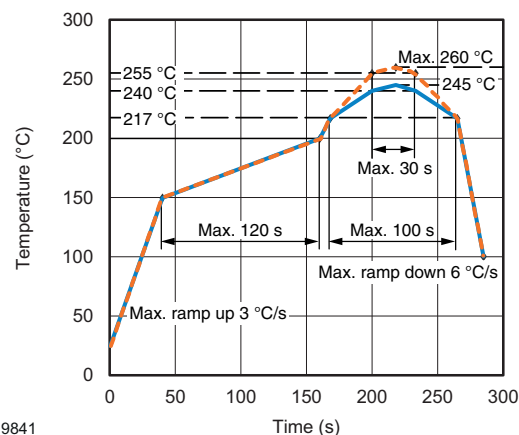
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at $40\text{ }^{\circ}\text{C}$ (+ 5 $^{\circ}\text{C}$), RH < 5 %

or

96 h at $60\text{ }^{\circ}\text{C}$ (+ 5 $^{\circ}\text{C}$), RH < 5 %

REFLOW SOLDER PROFILE



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